IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Robert Bartola et al.

Serial No.: 09/847,746

Filed: May 1, 2001

For: INTEGRATED COOLING OF A

PRINTED CIRCUIT BOARD STRUCTURE

Group Art Unit: 2835

Examiner: Datskovsky, Michael V.

ECENEU POR DOLLOGY CENTER 280

AMENDMENT AND RESPONSE TO OFFICE ACTION

Commissioner for Patents and Trademarks Washington, D.C. 20231

Sir:

12.

In response to the Office Action mailed July 25, 2002, kindly amend the application as follows:

In the Claims:

Please cancel claims 1-11 without prejudice to pursue in a continuation application, and please amend claim 12 as follows:

(Amended) An assembly comprising:

a heat-generating device attached to a printed circuit board (PCB), and

a thermal management system, the thermal management system comprising a heat sink having an interior lumen, and a coolant circulation channel at least partially formed in a layer of the

PCB, the coolant circulation channel being in fluid communication with the heat sink lumen.

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